

SOT969-1

plastic thin fine-pitch ball grid array package; 64 balls; body
4 x 4 x 0.8 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA64
Package type industry code	TFBGA64
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	27-9-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		3.9	-	4	4.1	mm
E	package width		3.9	-	4	4.1	mm
A	seated height		[tbd]	-	1.1	1.1	mm
A ₂	package height		0.75	-	0.8	0.85	mm
n ₂	actual quantity of termination		-	-	64	-	



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2. Package outline

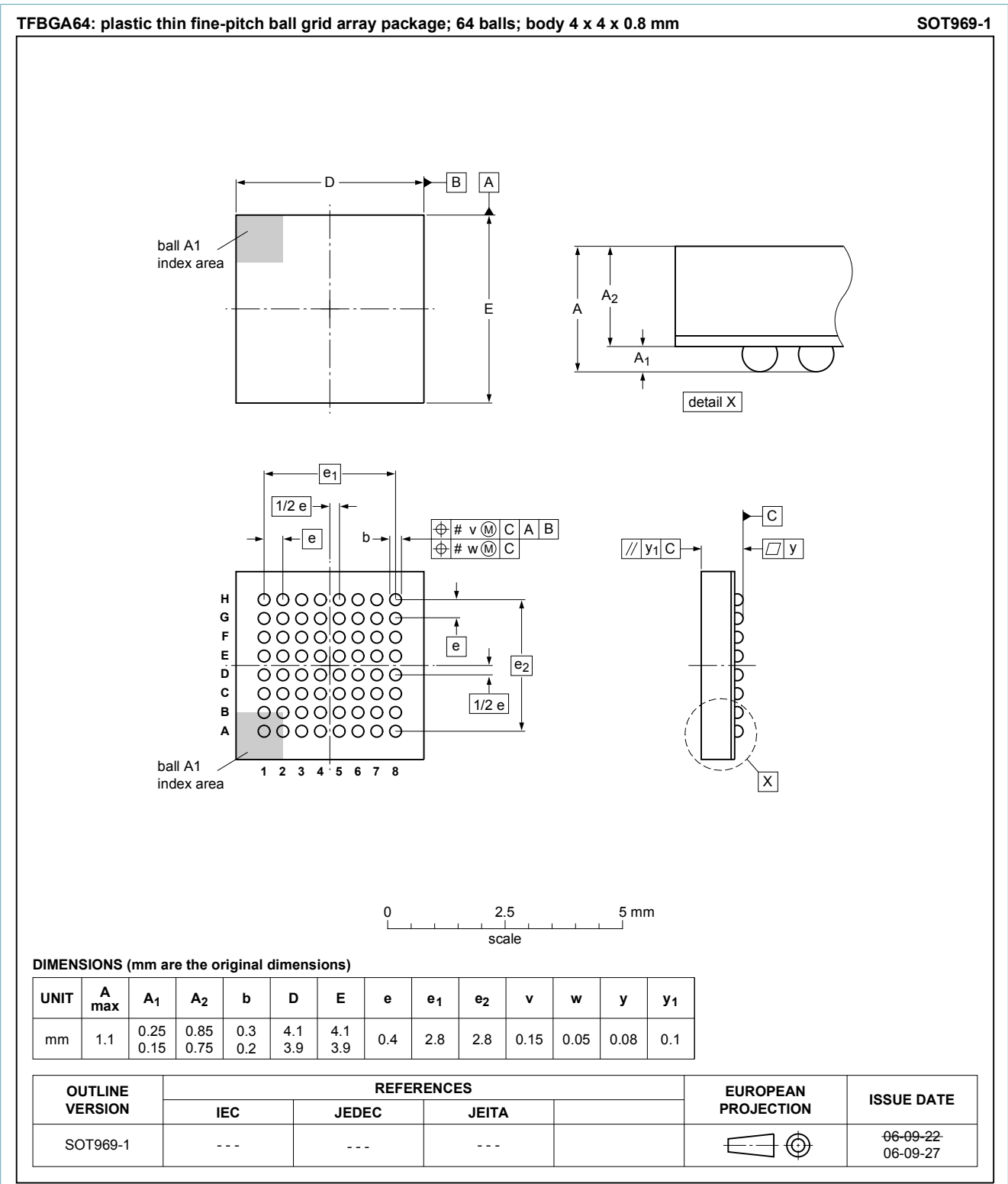


Fig. 1. Package outline TFBGA64 (SOT969-1)

3. Soldering

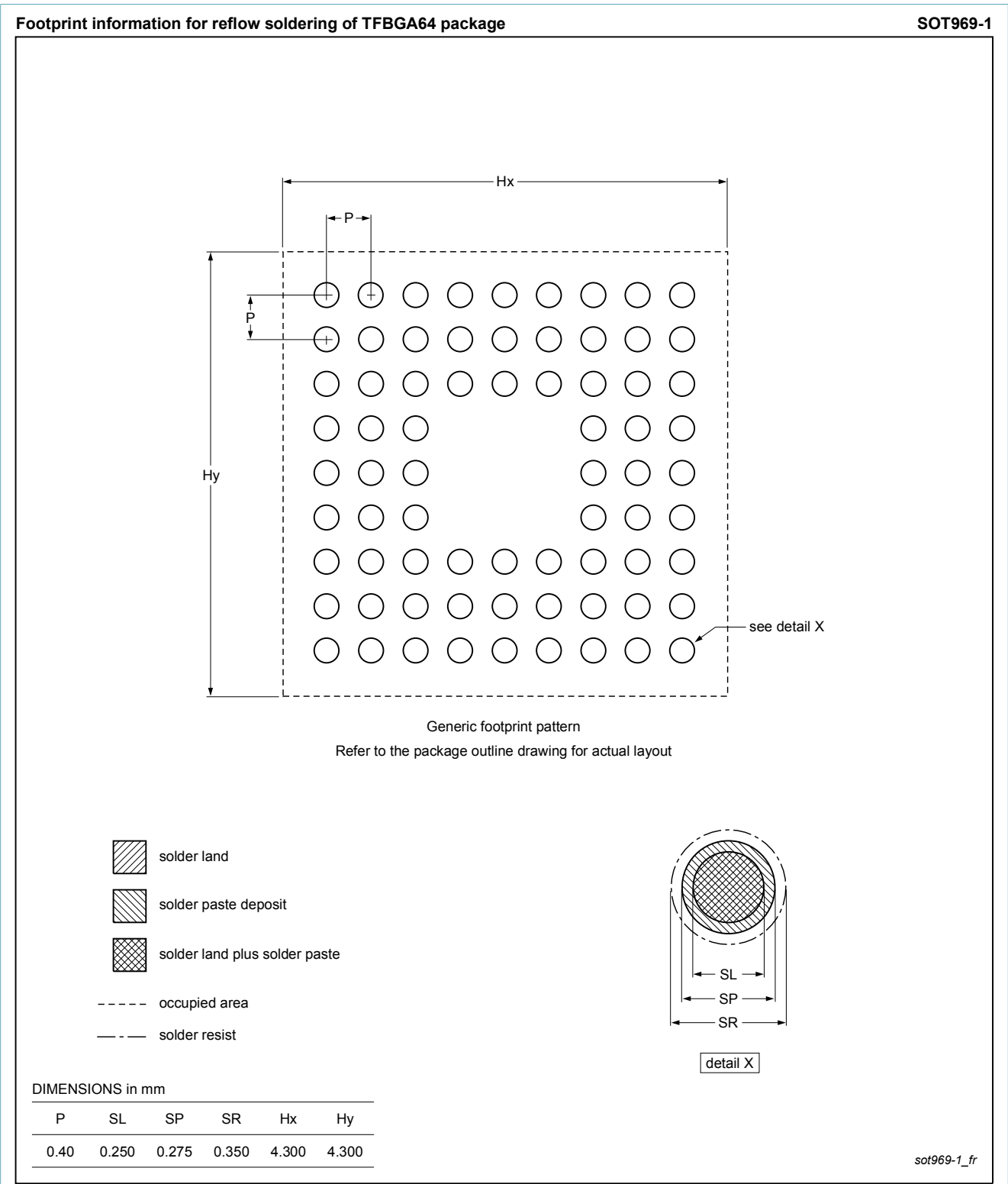


Fig. 2. Reflow soldering footprint for TFBGA64 (SOT969-1)

4. Legal information

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